



Dual 500mA LDO Regulator

Features

- Wide Input Voltage Range: 4.3V~6.5V
- $I_O = 500\text{mA}$, V_{OUT1} and V_{OUT2} Dropout Voltage Typically 1V
- Output Current in Excess of 500mA
- Output Voltage Accuracy $\pm 2\%$
- Quiescent Current, Typically 200 μA
- Internal Short Circuit Current Limit
- Internal Over Temperature Protection

Applications

- CD/DVD-ROM, CD/RW
- Wireless LAN Card/Keyboard/Mouse
- Battery-Powered Equipment
- XDSL Router

General Description

The G926A is a dual low dropout regulator with VOUT1 2.5V/500mA and VOUT2 3.3V/500mA, G926B is with VOUT1 1.8V/500mA and VOUT2 3.3V/500mA, G926C is with VOUT1 3.3V/500mA and VOUT2 2.5V/500mA and G926D is with VOUT1 3.3V/500mA and VOUT2 1.8V/500mA. The dropout voltage is typically 1V with 500mA load. A low quiescent current is typical 200 μA .

Familiar regulator features such as over temperature and current limit protection circuits are provided to prevent it from being damaged by abnormal operating conditions.

The G926 comes in a SOP-8 and SOP-8 (FD) with power-pad package.

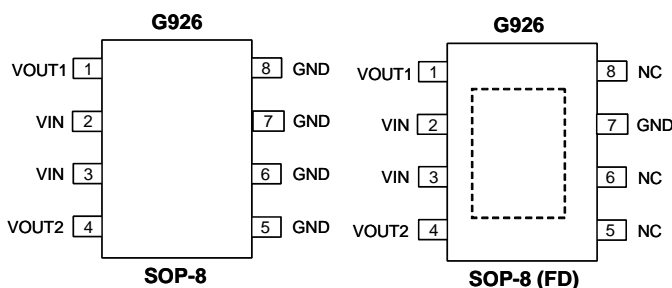
Ordering Information

ORDER NUMBER	MARKING	VOUT1	VOUT2	TEMP. RANGE	PACKAGE (Pb free)
G926AP1U	G926A	2.5V	3.3V	-40°C~ +85°C	SOP-8
G926BP1U	G926B	1.8V	3.3V	-40°C~ +85°C	SOP-8
G926CP1U	G926C	3.3V	2.5V	-40°C~ +85°C	SOP-8
G926DP1U	G926D	3.3V	1.8V	-40°C~ +85°C	SOP-8
G926AF1U	G926A	2.5V	3.3V	-40°C~ +85°C	SOP-8 (FD)
G926BF1U	G926B	1.8V	3.3V	-40°C~ +85°C	SOP-8 (FD)
G926CF1U	G926C	3.3V	2.5V	-40°C~ +85°C	SOP-8 (FD)
G926DF1U	G926D	3.3V	1.8V	-40°C~ +85°C	SOP-8 (FD)

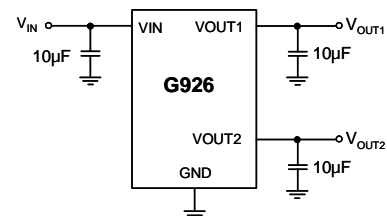
Note: P1: SOP-8 F1: SOP-8 (FD)

U: Tape & Reel

Pin Configuration



Typical Application Circuit





Absolute Maximum Ratings	(Note 1)
Input Voltage	7V
Power Dissipation Internally Limited	(Note2)
Maximum Junction Temperature	150°C
Storage Temperature Range	-65°C ≤ T _J ≤ +150°C
Reflow Temperature (soldering, 10sec)	260°C
Thermal Resistance Junction to Ambient	
SOP-8	162°C/W
SOP-8(FD)	75°C/W
Thermal Resistance Junction to Case	
SOP-8	31°C/W
SOP-8(FD)	5°C/W

Operating Conditions	(Note 1)
Input Voltage	4.3V ~ 6.5V
Temperature Range	-40°C ≤ T _A ≤ 85°C

Electrical Characteristics

V_{IN} = 5V, I_O = 500mA, C_{IN} = 1μF, C_{OUT} = 1μF. All specifications apply for T_A = T_J = 25°C. [Note 3]

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT	
Input Voltage	V _{IN}		4.3	---	6.5	V	
Output Voltage1	V _{OUT1}	G926A	I _O = 50mA	2.450	2.5	2.550	V
		G926B		1.764	1.8	1.836	
		G926C	10mA < I _O < 500mA	3.234	3.3	3.366	
		G926D		3.234	3.3	3.366	
Output Voltage 2	V _{OUT2}	G926A	10mA < I _O < 500mA	3.234	3.3	3.366	V
		G926B		3.234	3.3	3.366	
		G926C	I _O = 50mA	2.450	2.5	2.550	
		G926D		1.764	1.8	1.836	
Line Regulation	V _{line}	4V < V _{IN} < 6.5V, I _O = 10mA	---	0.3	1	%	
Load Regulation	V _{load}	10mA < I _O < 500mA	---	0.5	1	%	
Quiescent Current	I _Q	V _{IN} = 5V	---	200	500	μA	
Ripple Rejection	PSRR	fi=120Hz, V _{P-P} = 1V, V _O = 3.3V	---	53	---	dB	
		fi=120Hz, V _{P-P} = 1V, V _O = 2.5V	---	53	---		
		fi=120Hz, V _{P-P} = 1V, V _O = 1.8V	---	53	---		
Dropout Voltage	V _D	I _O = 500mA	---	1	1.2	V	
Short Circuit Current	I _{short}	V _{OUT1}	---	650	---	mA	
		V _{OUT2}	---	650	---		
Current Limit	I _{lim}	V _{OUT1}	550	800	---	mA	
		V _{OUT2}	550	800	---		
Over Temperature Threshold	T _{OT}		---	150	---	°C	
Over Temperature Hysteresis	T _{hys}		---	25	---	°C	

Note 1: Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Conditions are conditions under which the device functions but the specifications might not be guaranteed. For guaranteed specifications and test conditions see the Electrical Characteristics.

Note2: The maximum power dissipation is a function of the maximum junction temperature, T_{Jmax}; total thermal resistance, θ_{JA}, and ambient temperature T_A. The maximum allowable power dissipation at any ambient temperature is T_{Jmax}-T_A/θ_{JA}. If this dissipation is exceeded, the die temperature will rise above 150°C and IC will go into thermal shutdown. For the G926 in SOP-8 package, θ_{JA} is 162°C/W. For in SOP-8 (FD) with power-pad package, θ_{JA} is 75°C/W.

Note3: Low duty pulse techniques are used during test to maintain junction temperature as close to ambient as possible.

Note4: The type of output capacitor should be tantalum, aluminum or ceramic.

**Pin Description**

PIN		NAME	I/O	FUNCTION
SOP-8	SOP-8(FD)			
1	1	VOUT1	O	VOUT1 output voltage 2.5V in G926A, 1.8V in G926B or 3.3V in G926C and G926D, and source up to 500mA.
2,3	2,3	VIN	I	Input voltage
4	4	VOUT2	O	VOUT2 output voltage 3.3V in G926A and G926B, 2.5V in G926C or 1.8V in G926D, and source up to 500mA.
	5,6,8	NC	I	No Connection
5,6,7,8	7	GND	I	Ground also function as heat-sink.

Definitions**Dropout Voltage**

The input/output Voltage differential at which the regulator output no longer maintains regulation against further reductions in input voltage. Measured when the output drops 100mV below its nominal value, dropout voltage is affected by junction temperature, load current and minimum input supply requirements.

Line Regulation

The change in output voltage for a change in input voltage. The measurement is made under conditions of low dissipation or by using pulse techniques such that average chip temperature is not significantly affected.

Load Regulation

The change in output voltage for a change in load current at constant chip temperature. The measurement is made under conditions of low dissipation or by using pulse techniques such that average chip temperature is not significantly affected.

Maximum Power Dissipation

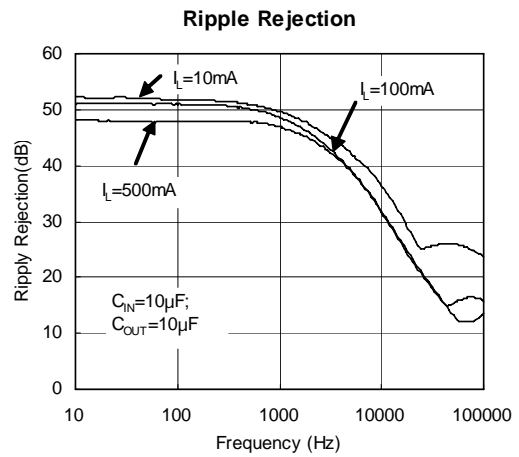
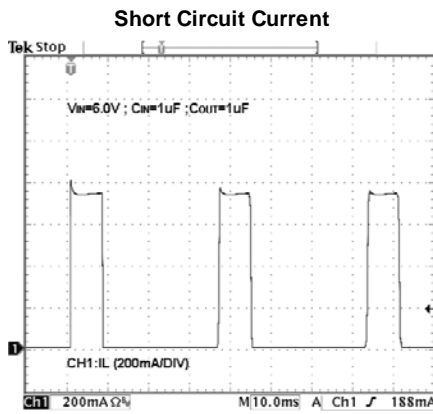
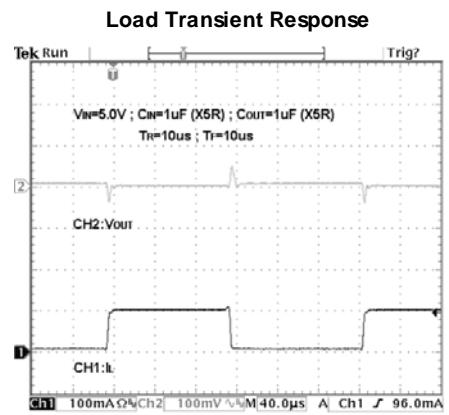
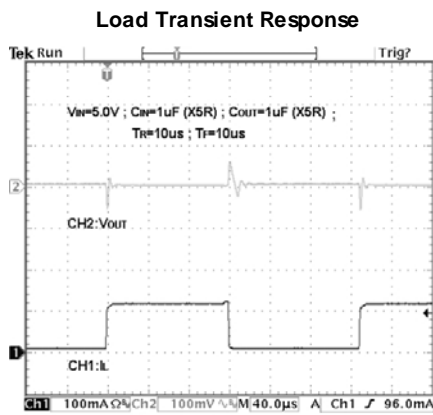
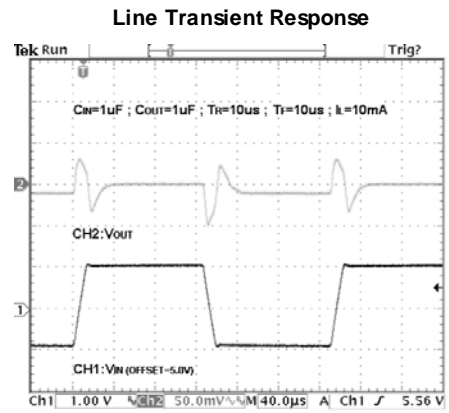
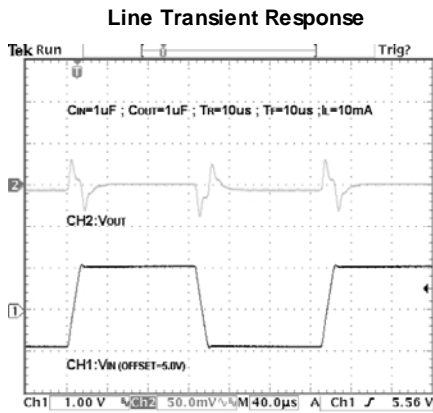
The maximum total device dissipation for which the regulator will operate within specifications.

Quiescent Bias Current

Current which is used to operate the regulator chip and is not delivered to the load.

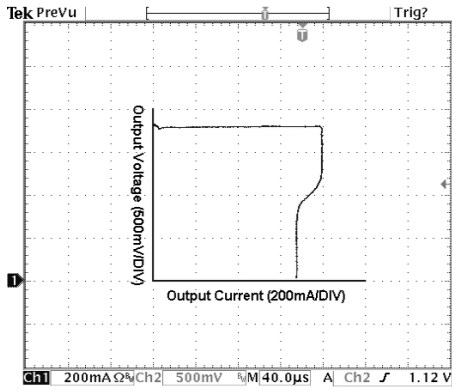
Typical Performance Characteristics

($V_{IN}=5V$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$, $T_A=25^\circ C$, unless otherwise noted.)

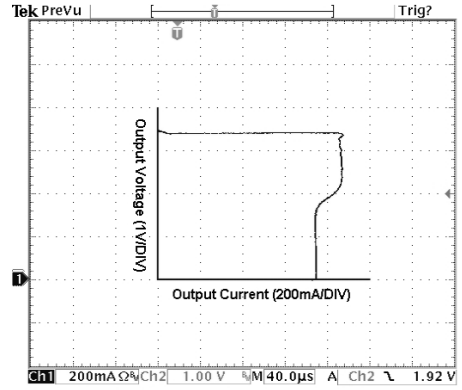


Typical Performance Characteristics (continued)

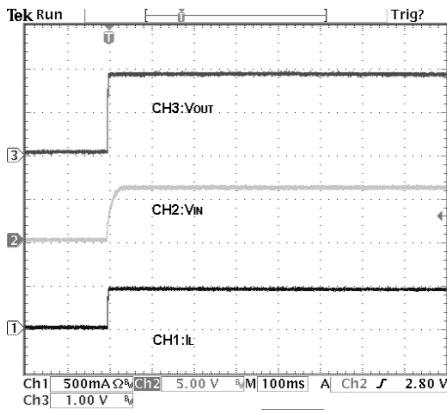
Overcurrent Protection Characteristics



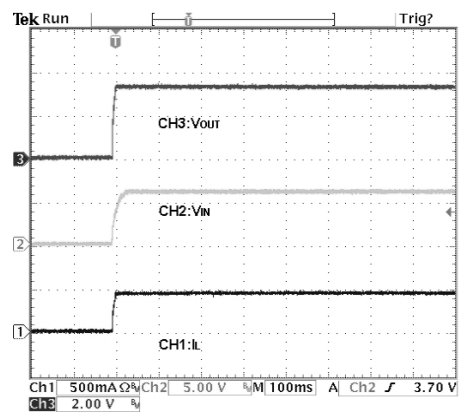
Overcurrent Protection Characteristics



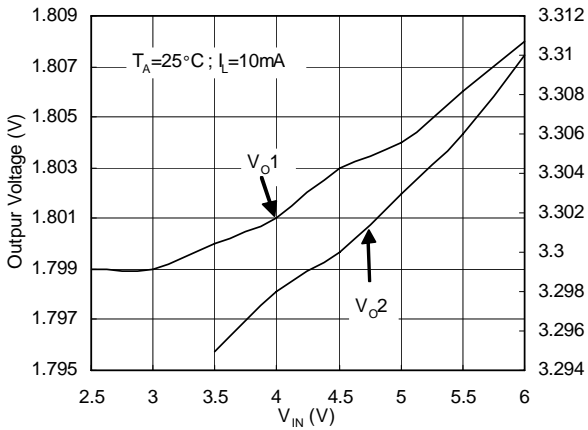
Start-up



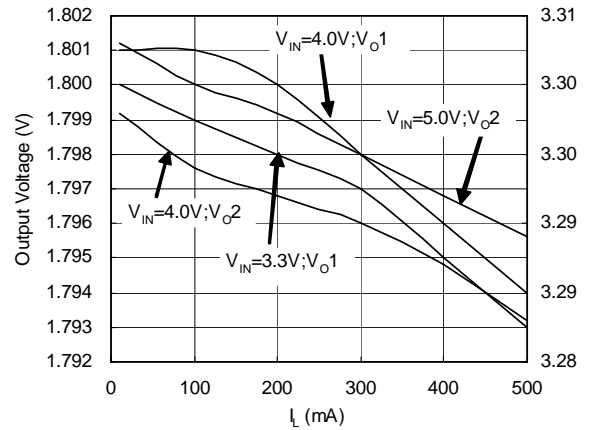
Start-up



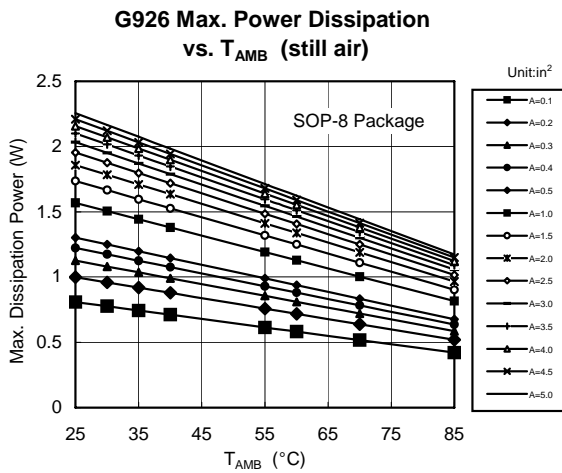
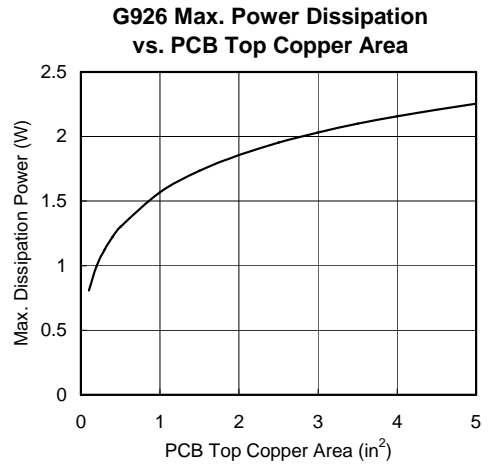
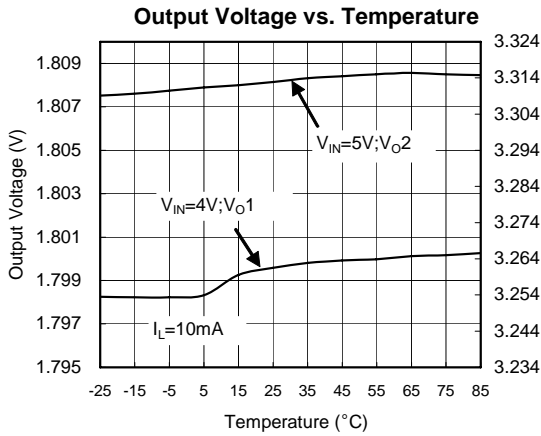
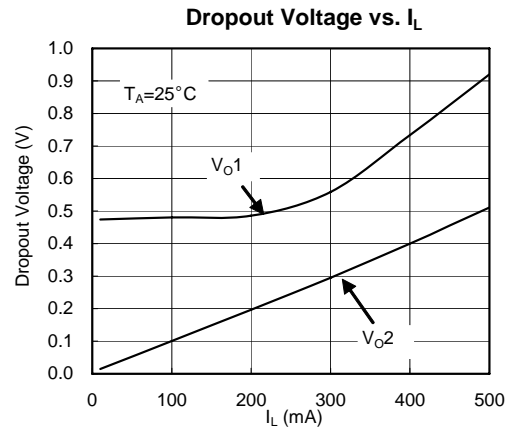
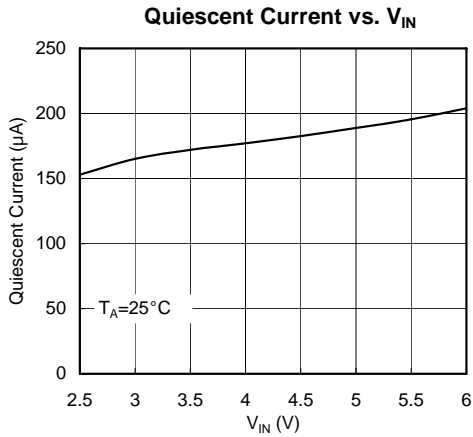
Output Voltage vs. V_{IN}



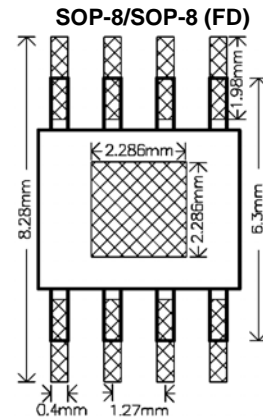
Output Voltage vs. I_L



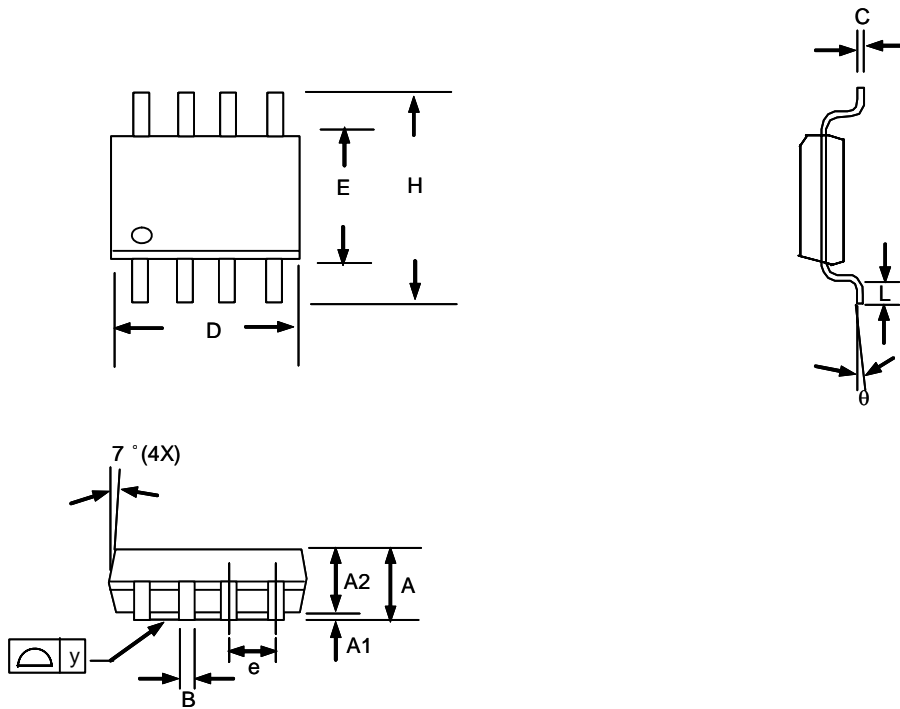
Typical Performance Characteristics (continued)



Recommended Minimum Footprint



Package Information

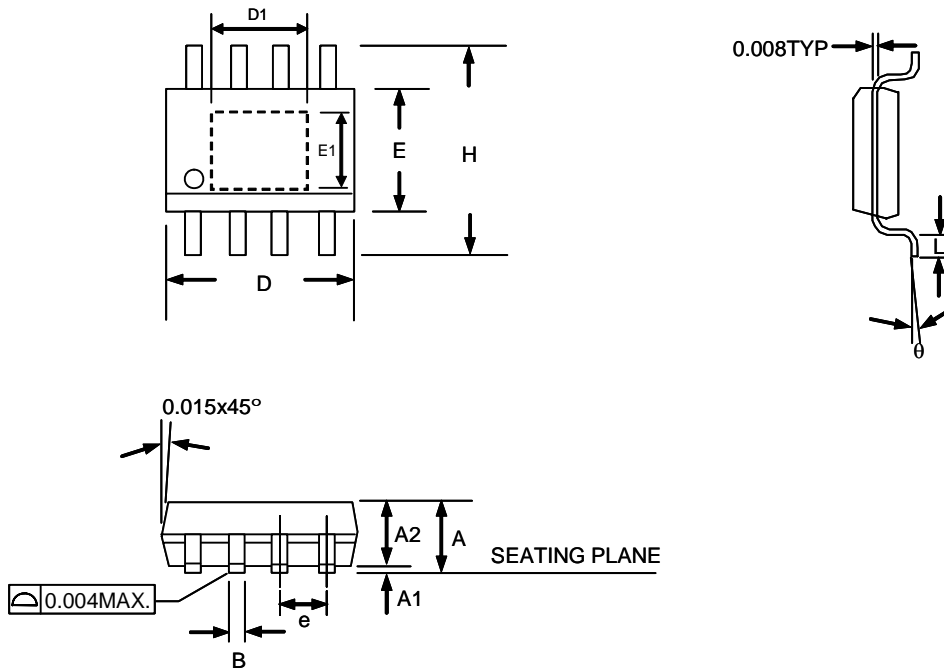


SOP-8 Package

Note:

1. Package body sizes exclude mold flash and gate burrs
2. Dimension L is measured in gage plane
3. Tolerance 0.10mm unless otherwise specified
4. Controlling dimension is millimeter converted inch dimensions are not necessarily exact.
5. Followed from JEDEC MS-012

SYMBOL	DIMENSION IN MM			DIMENSION IN INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.35	1.60	1.75	0.053	0.063	0.069
A1	0.10	-----	0.25	0.004	-----	0.010
A2	-----	1.45	-----	-----	0.057	-----
B	0.33	-----	0.51	0.013	-----	0.020
C	0.19	-----	0.25	0.007	-----	0.010
D	4.80	-----	5.00	0.189	-----	0.197
E	3.80	-----	4.00	0.150	-----	0.157
e	-----	1.27	-----	-----	0.050	-----
H	5.80	-----	6.20	0.228	-----	0.244
L	0.40	-----	1.27	0.016	-----	0.050
y	-----	-----	0.10	-----	-----	0.004
θ	0°	-----	8°	0°	-----	8°



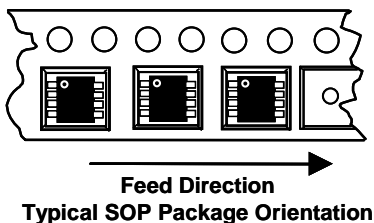
SOP-8 (FD) Package

Note:

1. JEDEC Outline: MS-012 AA/E.P. Version: N/A
2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusions and gate burrs shall not exceed .15mm (.006in) per side.
3. Dimensions "E" does not include inter-lead flash, or protrusions inter-lead flash and protrusions shall not exceed .25mm (.010in) per side.

SYMBOL	DIMENSION IN MM		DIMENSION IN INCH	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.00	0.13	0.000	0.005
A2	-----	1.50	-----	0.059
B	0.41TYP		0.016TYP	
D	4.80	4.98	0.189	0.196
E	3.81	3.99	0.150	0.157
e	1.27TYP		0.05TYP	
H	5.80	6.20	0.228	0.244
L	0.41	1.27	0.016	0.050
θ	0°	8°	0°	8°
D1	-----	2.29	-----	0.090
E1	-----	2.29	-----	0.090

Taping Specification



PACKAGE	Q'TY/REEL
SOP-8	2,500 ea
SOP-8 (FD)	2,500 ea

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